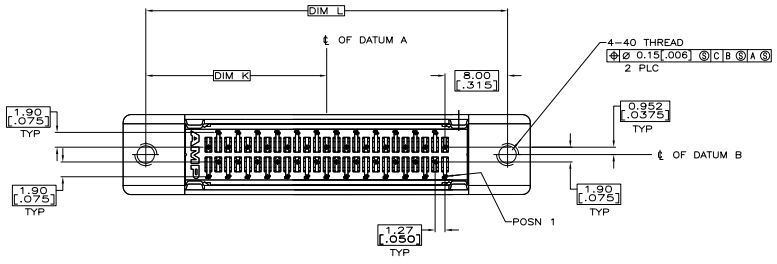


- △ POSITION TOLERANCE APPLIES AT CONTACT TIP.
- △ POSITION NUMBERS SHOWN FOR REFERENCE ONLY.
- △ MATERIAL:  
 HOUSING - POLYPHTHALAMIDE, BLACK, UL 94-V0 RATED.  
 SHELL - CARBON STEEL PER ASTM A109.  
 CONTACTS - PHOSPHOR BRONZE PER QQ-B-750.  
 BRACKET - ZINC.
- △ FINISH:  
 SHELL - 5.08µm [.000200] MIN NICKEL OVER 1.27µm [.000050] MIN COPPER.  
 BRACKET - 3.81µm [.000150] MIN NICKEL OVER 5.08µm [.000200] MIN COPPER.  
 CONTACTS - EITHER 0.76µm [.000030] MIN GOLD PLATE OR GOLD FLASH OVER PALLADIUM NICKEL, 0.76µm [.000030] MIN TOTAL, FOR A LENGTH OF 0.64 [.025] MIN, 0.13 [.005] MAX FROM MATING END, 1.27µm [.000050] MIN TIN ON OPPOSITE END FOR A LENGTH OF 4.78 [.188] MIN, ALL OVER 1.27µm [.000050] MIN NICKEL UNDERPLATE.
- △ PCB BOARD HOLE RECOMMENDATIONS:  
 A. HOLES SHOULD BE DRILLED WITH A 0.701 [.0276] DRILL.  
 B. PCB BOARD PLATING TO BE 7.62µm [.000300] MIN TIN OVER 0.025-0.038 [.0010-.0015] COPPER.  
 C. RECOMMENDED HOLE SIZE AFTER TIN PLATING IS 0.56-0.66 [.022-.026].
- △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



OBSOLETE	PER DETAIL X	96.90 [3.815]	74.93 [2.950]	79.15 [3.116]	90.93 [3.580]	45.47 [1.790]	120	4-5786555-0
	PER DETAIL X	84.20 [3.315]	62.23 [2.450]	66.45 [2.616]	78.23 [3.080]	39.12 [1.540]	100	5786555-9
	PER DETAIL X	63.88 [2.515]	41.91 [1.650]	46.13 [1.816]	57.91 [2.280]	28.96 [1.140]	68	5786555-7
	PER DETAIL Y	52.45 [2.065]	30.48 [1.200]	34.70 [1.366]	46.48 [1.830]	23.24 [.915]	50	5786555-5
OBSOLETE	PER DETAIL X	33.40 [1.315]	11.43 [.450]	15.65 [.616]	27.43 [1.080]	13.72 [.540]	20	5786555-1
	RECOMMENDED PCB MTG DIMENSIONS	R	P	N	L	K	NO OF POSN	PART NO

THIS DRAWING IS A CONTROLLED DOCUMENT. THE MASTER IS KEPT AT THE MANUFACTURING SITE.

TE Connectivity  
 RECEPTACLE ASSEMBLY, SHIELDED, VERTICAL, FLAT TOP, ACTION PIN FOR .062 TO .093 THICK BO.

114-40029  
 108-1228  
 100779 (C=5786555)